

WHAT IS CLAIMED IS:

1. An integrated electronic component comprising:  
a ceramic substrate including circuit elements; and  
a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate;  
wherein bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a tapered shape having obtuse angles with respect to the bottom edges of the substrate-facing segments.
2. An integrated electronic component according to Claim 1, wherein the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top surface of the ceramic substrate, and the substrate-facing segments are separated from the top surface, thereby the substrate-facing segments being supported at borders with the side segments in a cantilevered fashion.
3. An integrated electronic component according to Claim 1, wherein the circuit elements are disposed within the ceramic substrate.
4. An integrated electronic component according to Claim 1, wherein the circuit elements are mounted on the ceramic substrate.

5. An integrated electronic component according to Claim 1, wherein the metal case is of at least one of phosphor bronze and nickel silver.

6. An integrated electronic component according to Claim 1, wherein the ceramic substrate includes a plurality of laminated ceramic sheets.

7. An integrated electronic component according to Claim 1, wherein the metal case has a substantially box-like shape.

8. An integrated electronic component according to Claim 1, wherein the obtuse angles are within the range of  $145^{\circ} \leq \theta \leq 170^{\circ}$ .

9. An integrated electronic component according to Claim 1, wherein each of the notches has a length in a first direction that is within the range of about 0.25 mm to about 0.30 mm and a length in a second direction that is within the range of about 0.05 mm to about 0.15 mm.

10. An integrated electronic component according to Claim 1, wherein the ceramic substrate has a length of about 5.0 mm to about 6.5 mm, and has a width of about 4.0 mm to about 4.5 mm.

11. An integrated electronic component comprising:  
a ceramic substrate including circuit elements; and  
a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate;

wherein bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a substantially circular arc shape.

12. An integrated electronic component according to Claim 11, wherein the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top surface of the ceramic substrate, and the substrate-facing segments are separated from the top surface, thereby the substrate-facing segments being supported at borders with the side segments in a cantilevered fashion.

13. An integrated electronic component according to Claim 11, wherein the circuit elements are disposed within the ceramic substrate.

14. An integrated electronic component according to Claim 11, wherein the circuit elements are mounted on the ceramic substrate.

15. An integrated electronic component according to Claim 11, wherein the metal case is of at least one of phosphor bronze and nickel silver.

16. An integrated electronic component according to Claim 11, wherein the ceramic substrate includes a plurality of laminated ceramic sheets.

17. An integrated electronic component according to Claim 11, wherein the metal case has a substantially box-like shape.

18. An integrated electronic component according to Claim 11, wherein a radius of curvature  $R$  of the notches is about 0.05 mm to about 0.2 mm.

19. An integrated electronic component according to Claim 11, wherein the ceramic substrate has a length of about 5.0 mm to about 6.5 mm, and has a width of about 4.0 mm to about 4.5 mm.